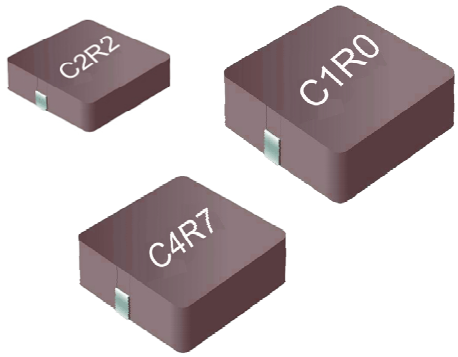
SMD Molding Power Inductor

◆ Features

1、Magnetically shielded construction, low DC resistance;
2、The use of magnetic iron powder ensure capability for large current;
3、Low audible core noise;
4、Ideal for DC-DC converter applications in hand held personal computer and etc;
5、Frequency Range: up to 3.0MHz;
6、RoHS compliant。



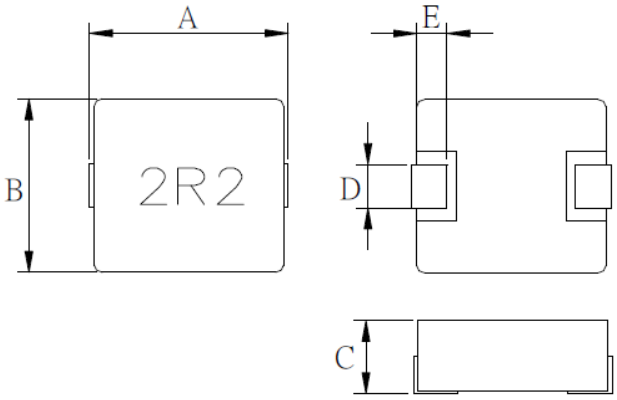
◆ Applications

1、Smart phone、MID;
2、Next-generation mobile devices with multifunction such as adding color TV and digital movie cameras;
3、Flat-screen TVs, blue-ray disc recorders, set top box;
4、Notebooks, desktop computers, servers, graphic cards;
5、Portable gaming devices, personal navigation systems, personal multimedia devices;
6、Automotive systems;
7、Telecomm base stations。

◆ Lead Free Part Numbering

SLO	1770	H	2R2	M	T	T
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Series Type
(2) Dimension：A X C
(3) Material Code
(4) Inductance：2R2=2.2μH；
100=10μH；101=100μH
(5) Inductance Tolerance：M=±20%, Y=±30%
(6) Company Code
(7) Packaging：packed in embossed carrier tape



◆ Dimensions

Series	A (mm)	B (mm)	C (mm)	D±0.3 (mm)	E±0.3 (mm)
SLO1770H	17.50 Max	17.50 ±0.1	7.0 Max	11	2.0

◆ Specification

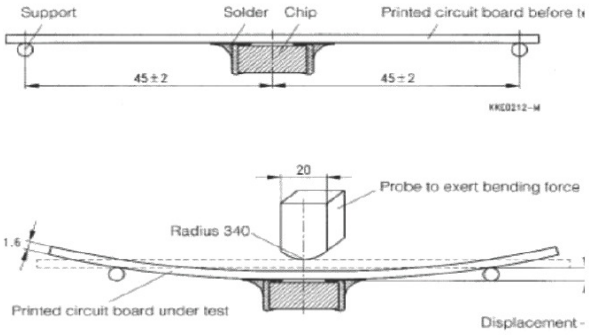
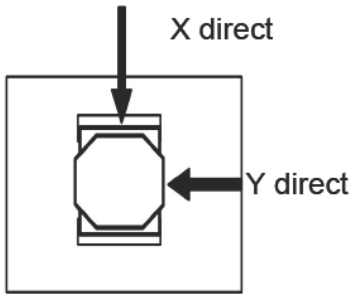
Part Number	INDUCTANCE Lo(μ H)	Rdc (mΩ) Max	Test a condition	SATURATION CURRENT(Isat) DC AMPS2 (Typ.)	HEAT RATING CURRENT(Idc) DC AMPS1 (Typ.)
SLO1770H Series					
SLO1770H1R5MTT	1.5	2.3	100KHz/1V	40	31
SLO1770H2R2MTT	2.2	2.5	100KHz/1V	34	29
SLO1770H3R3MTT	3.3	3.95	100KHz/1V	30	24
SLO1770H4R7MTT	4.7	4.75	100KHz/1V	24	21
SLO1770H6R8MTT	6.8	7.5	100KHz/1V	22	17
SLO1770H8R2MTT	8.2	8.7	100KHz/1V	20	13
SLO1770H100MTT	10	9.9	100KHz/1V	19	12
SLO1770H150MTT	15	17	100KHz/1V	14.5	11
SLO1770H220MTT	22	23	100KHz/1V	11.5	8.5
SLO1770H330MTT	33	37	100KHz/1V	10	8.0
SLO1770H470MTT	47	47	100KHz/1V	7.5	6.0
SLO1770H680MTT	68	85	100KHz/1V	6.5	5.2
SLO1770H101MTT	100	130	100KHz/1V	5.0	3.7

NOTES:

1. DC current (Idc) that will cause an approximate △T of 40℃
2. DC current (Isat) that will cause Lo to drop approximately 20%
3. All test data is referenced to 25℃ ambient
4. Operating Temperature Range -55℃ to +150℃
5. The part temperature (ambient + temp rise) should not exceed 150℃ under the worst operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

◆ Reliability Test

<table>
<tr><th>Item</th><th>Specification and Requirement</th><th>Test Method</th></tr>
<tr><td>Solderability</td><td>1. No case deformation or change in apperarance
2. New solder coverage More than 90%</td><td>1.Preheat：155℃±5℃ ，60S±2S
2.Tin: lead-free.
3.Temperature:245℃±5℃，flux 3.0S±0.5S.</td></tr>
<tr><td>Mechanical shock</td><td>1. No case deformation or change in apperarance
2. △L/Lo≦±10%</td><td>1. Acceleration： 100G
2. Pulse time:：6ms
3. 3 times in each positive and negative direction of 3 mutual perpendicular directions</td></tr>
<tr><td>Mechanical vibration</td><td>1. No case deformation or change in apperarance
2. △L/Lo≦±10%</td><td>1. The test samples shall be soldered to the board. Then it shall be submitted to below test conditions.
<table>
<tr><td>Fre. Range</td><td>10~55Hz</td></tr>
<tr><td>Total Amplitude</td><td>1.5mm</td></tr>
<tr><td>Sweeping Method</td><td>10Hz to 55Hz to 10Hz</td></tr>
<tr><td>Time</td><td>For 2 hours on each X,Y,Z axis.</td></tr>
</table>
2. Recovery: At least 2 hours of recovery under the standard condition after the test, followed by the measurement within 24 ±2 hours.</td></tr>
<tr><td>Thermal Shock</td><td>Inductance change:
Within ± 10% Without distinct damage in appearance</td><td>1. First -55℃ for 30 minutes，last 125℃ for 30 minutes as 1 cycle. Go through 1000 cycles.
2. Max transfer time is 2 minutes.
3. Measured at room temperature after placing for 24±2 hours</td></tr>
<tr><td>Humidity Resistance</td><td>Inductance change:
Within ± 10% Without distinct damage in appearance</td><td>1.Reflow 2 times,
2.85℃,85%RH,1000 hours
3.Measured at room temperature after placing for 24±2 hours</td></tr>
<tr><td>Low temperature storage</td><td>Inductance change:
Within ± 10% Without distinct damage in appearance</td><td>1. Temperature：-55 ± 2℃
2. Time：1000 hours
3. Measured at room temperature after placing for 24±2 hours</td></tr>
<tr><td>High temperature storage</td><td>Inductance change:
Within ± 10% Without distinct damage in appearance</td><td>1. Temperature：+125 ± 2℃
2. Time：1000 hours
3. Measured at room temperature after placing for 24±2 hours</td></tr>
</table>

Board Flex	Inductance change: Within ± 10% Without distinct damage in appearance	1、Run through IR reflow for 2 times； 2、Place the 100mm X 40mm board into a fixture similar to the one shown in below Figure with the component facing down 3、The apparatus shall consist of mechanical means to apply a force which will bend the board (D) x = 2 mm minimum. 4、The duration of the applied forces shall be 60±5 sec. The force is to be applied only once to the oard. 
Terminal Strength	No removal or split of the termination or other defects shall occur.	1、The test samples shall be soldered to the board 2、Push the product vertically from the side of the sample using the thrust tester. 3、Automotive electronics：17.7N，60S±1s，X ，Ydirect. 

◆ Recommended Soldering Technologies

(1) Re-flowing Profile

Preheat condition: 150 ~200℃/60~180sec.

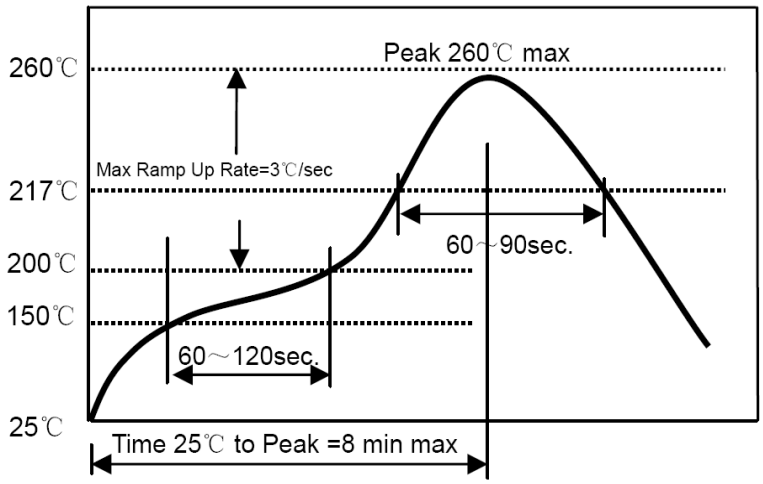
Allowed time above 217℃: 80~120sec.

Max temp: 260℃

Max time at max temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max



(2) Iron Soldering Profile

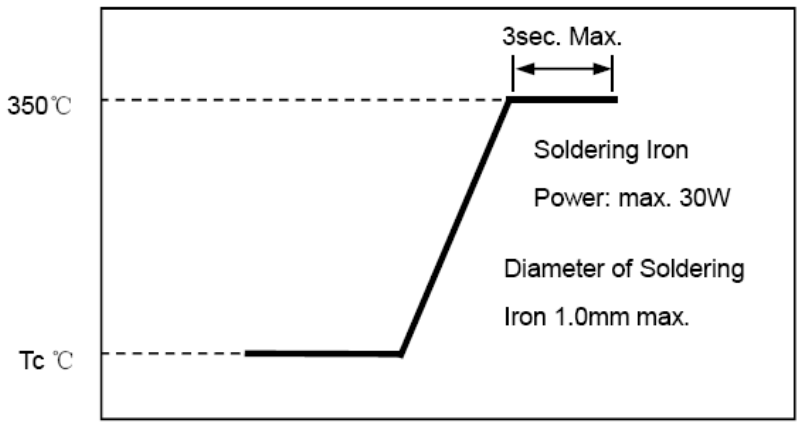
Iron soldering power: Max. 30W

Pre-heating: 150℃/60sec.

Soldering time: 3sec. Max.

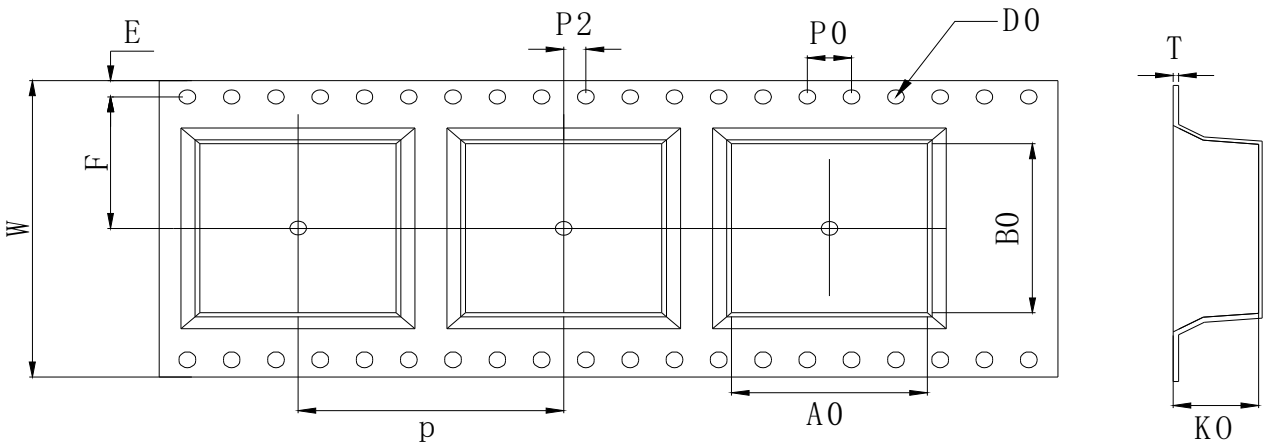
Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering



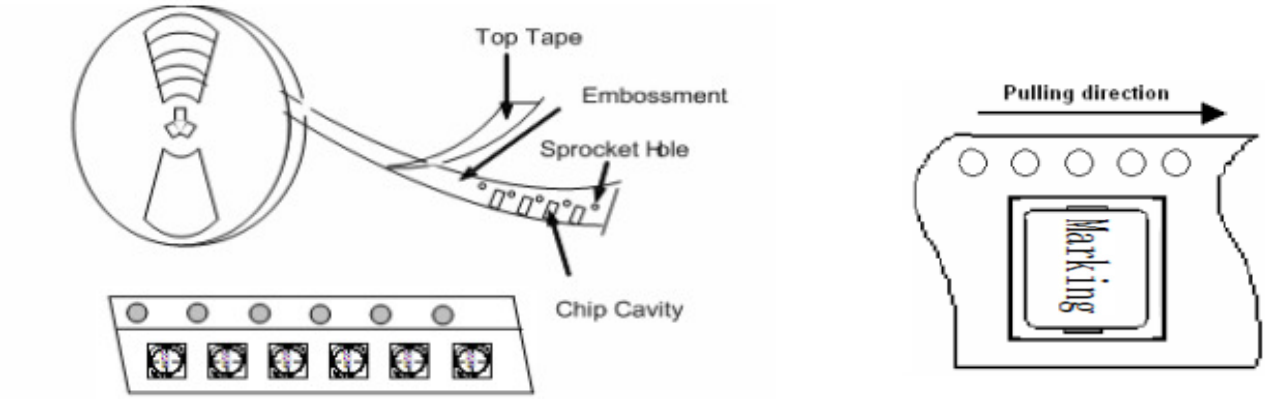
◆ Packaging Information

(1) Tape Packaging Dimensions（Unit：mm）

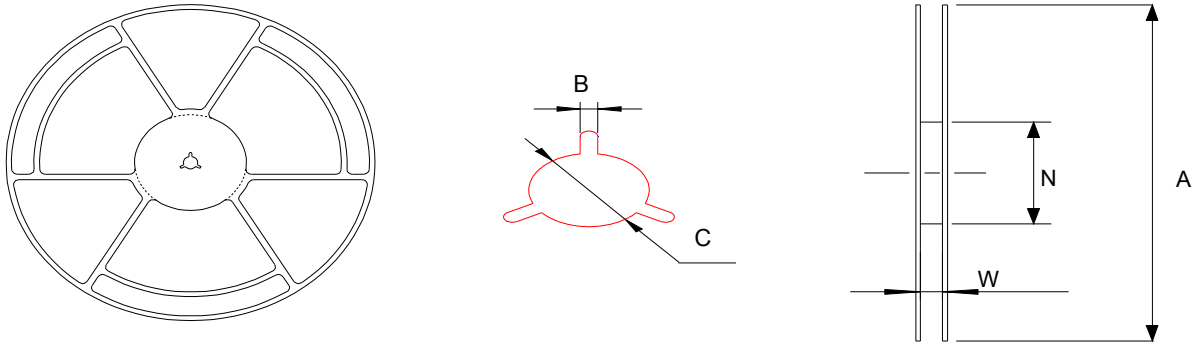


Type	Tape dimensions (mm)										
	W	P	P0	P2	D0	T	A0	B0	K0	E	F
CMLO1770	32 ±0.3	24 ±0.1	4.0 ±0.1	2.0 ±0.1	1.5 ±0.1	0.5 ±0.05	17.5 ±0.1	18.1 ±0.1	7.3 ±0.1	1.75 ±0.1	14.2 ±0.1

Taping Drawings (UNIT:mm)



(2) Reel Dimensions（Unit：mm）



A	W	N	B	C
330±2.0	32.0±0.5	97±0.5	2.3±0.3	13.0±0.2

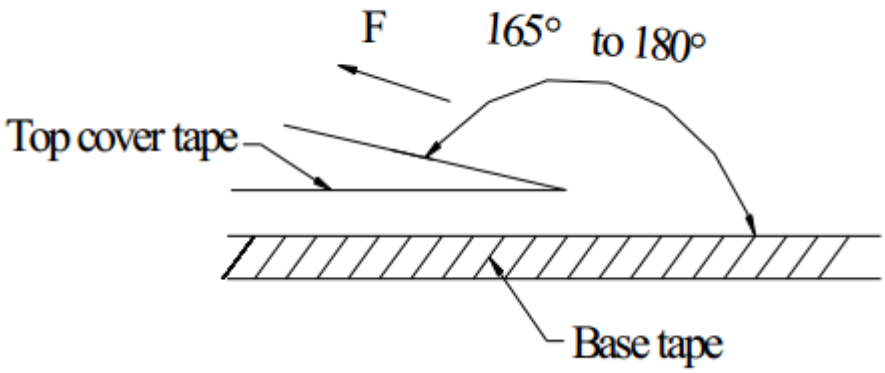
(3) Packaging Quantity(PCS)

Type	Standard Quantity		
	Reel	Inner box	Carton box
SLO1770	200 pcs / reel	2Reel / box (400 pcs)	3 Middle boxes, (1200 pcs)

(4) Peel force of top cover tape

The peel speed shall be about 300mm/minute

The peel force of top cover tape shall be between 0.1 to 1.3 N



Unikeyic Electronics

Global Electronic Components Distributor

Click to view pricing, inventory, delivery, and lifecycle information:

Sunltech:

SLO252010T4R7MTT SLS6D28S680MTT SLO201610T2R2MTT S617DB1023 SLP7045S220MTT
SLS4D28S100MTT SLW4020P1R0MST SMW3216B102ATE STCM11+ SLO160808T2R2MTT
SLD10D50S151MTT SLP1265S220MTT SLS6D38S3R3NTT SMW4532S201XTT STC11T+
SCA1111H47NJTT SLO1235HR47MTT SLP1045S101MTT SLW4012S100MST SCA0806H19NJTT
SLF1005-221KTT SLH1204S150MTT SLM20162R2MIT SLO1040H680MTT SLO252010F4R7MTT
SMABA008482CE1A40 SMW5045S601NTT SLO1770H1R5MTT SLO0624H100MTT SLQ1608C101MTT